Ettus USRP B310 (OEM) Specifications

2026-11-06

Contents

Ettus USRP B310 (OEM) Specifications. 3

Ettus USRP B310 (OEM) Specifications

Ettus USRP B310 (OEM) Specifications

These specifications apply to the Ettus USRP B310 (OEM) variant.

The Ettus USRP B310 has more than one form factor: USRP B310 (OEM), USRP B310 (Enclosed), and USRP B310 (PCIe). This document refers to the USRP B310 (OEM) variant. Refer to the specifications for your respective Ettus USRP B310 form factor for variant-specific information.

Revision History

Version	Date changed	Description
379307A-01	August 2026	Initial release.

Looking For Something Else?

For information not found in the specifications for your product, such as operating instructions, browse *Related Information*.

Related information:

- Ettus USRP B310 User Manual
- USRP B3xx Series Hardware Driver and Device Manual
- USRP B310 (OEM) Safety, Environmental, and Regulatory Information
- Software and Driver Downloads
- Dimensional Drawings
- Product Certifications
- Letter of Volatility
- Discussion Forums
- NI Learning Center

Definitions

Warranted Specifications describe the performance of a model under stated operating conditions and are covered by the model warranty.

Characteristics describe values that are relevant to the use of the model under stated operating conditions but are not covered by the model warranty.

- **Typical**—describes the performance met by a majority of models.
- **Nominal**—describes an attribute that is based on design, conformance testing, or supplemental testing.
- **Measured**—describes the measured performance of a representative model.

Values are *Measured* unless otherwise noted.

Conditions

Specifications are valid under the following conditions unless otherwise noted.

- Specifications are valid at 23 °C ambient temperature.[1]
- Specifications that reference dBFS are based on a full-scale digital level at the ADC or DAC interface.
- Specifications utilize default UHD 4.11.0 software configuration and a 122.88 MHz MCR (Master Clock Rate).

Software

Table 1. Software

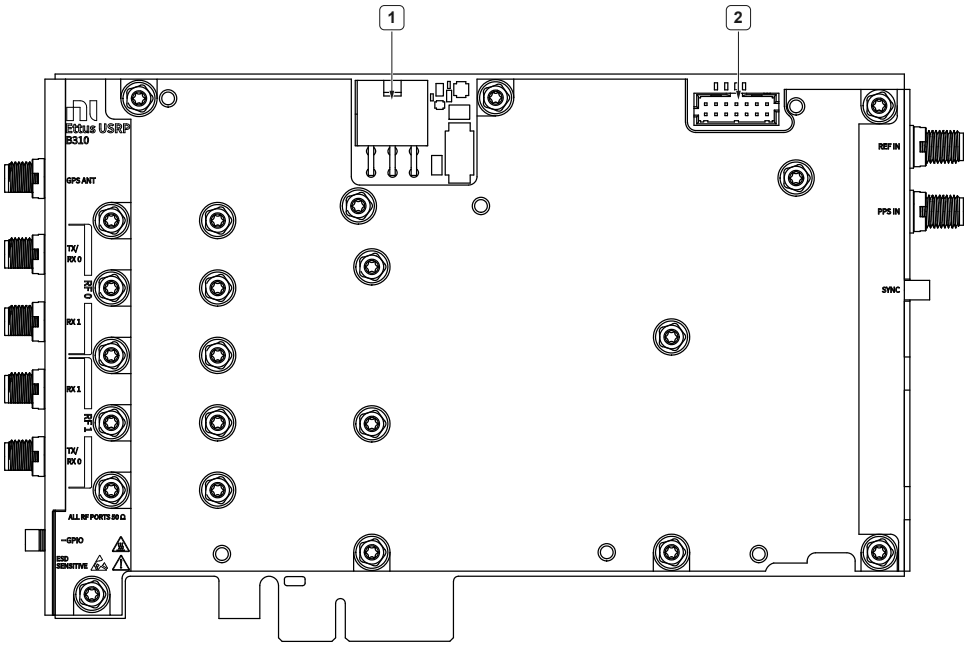
Device software	USRP Hardware Driver™ version 4.11.0 or later
FPGA framework	RFNoC
Application environments	GNU Radio
Programming languages	C/C++, Python

1. The operating temperature is the recommended ambient temperature around the product with the PCIe variant integration (NI Part Number: 790817-01—PCIe). Higher operating temperatures might be achieved with active cooling such as fans or liquid cooling.

USRP B310 (OEM) Front/Rear Panel

Overview of the front and rear panel elements of the Ettus USRP B310.

Figure 1. USRP B310 (OEM) Front/Rear Panels



1. AUX Power (J10)
2. JTAG (J13)

Table 2. Port/Connector Descriptions

Port/Connector Name	Description	Connector Type
GPS ANT	Input for an external GPS antenna used by the onboard GPSDO.	• SMA (f), 50 Ω • 3.0 V, 0.19 W
TX/RX 0	Bidirectional radio frequency signal connector used for transmit and receive operations.	• SMA (f), 50 Ω • RX—+10 dBm input power damage level • TX—+20 dBm, maximum
RX 1	Radio frequency signal connector used for receive-only operations.	• SMA (f), 50 Ω

Port/Connector Name	Description	Connector Type
		• RX—Receive only; +10 dBm input power damage level
GPIO	General purpose input/output digital terminals.	• Mini HDMI Type-C • 3.3 V output voltage • 250 mA VCC out, 8 mA per GPIO output port • NOT AN HDMI-COMPATIBLE INTERFACE
Console JTAG (J13)	For connecting to the FPGA for development and debugging. Provides access to JTAG.	• 2 V DC, maximum
SYNC	For use with sharing a high-frequency reference and PPS across multiple Ettus USRP B310 devices.	• Mini HDMI Type-C • Reference Clock Output—AC coupled output ±0.325 V (0.65 V peak-peak) • PPS Output—0 V to 3.3 V • NOT AN HDMI-COMPATIBLE INTERFACE
PPS IN	Input for an external pulse-per-second (PPS) signal used for time synchronization.	• SMA (f), 50 Ω • +3.3 V, input only
REF IN	Input for an external 10 MHz reference clock signal used for frequency synchronization.	• SMA (f), 50 Ω • ±0.165 V to ±0.45 V (0.33 V to 0.9 V peak-peak), input only

Figure 2. GPIO Connector Pinout

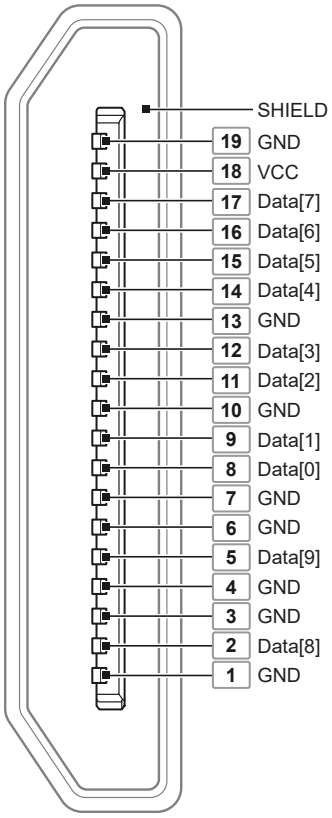


Table 3. GPIO Connector Pinout

Pin	Name	Direction	Voltage Domain	Description
—	SHIELD	N/A	N/A	SHIELD
19	GND	N/A	N/A	Ground reference
18	VCC	Out	+3.3 V	External power for GPIO accessories (250 mA maximum)
17	Data[7]	In/Out	3.3 V	General-purpose digital I/O
16	Data[6]	In/Out	3.3 V	General-purpose digital I/O
15	Data[5]	In/Out	3.3 V	General-purpose digital I/O
14	Data[4]	In/Out	3.3 V	General-purpose digital I/O

Pin	Name	Direction	Voltage Domain	Description
13	GND	N/A	N/A	Ground reference
12	Data[3]	In/Out	3.3 V	General-purpose digital I/O
11	Data[2]	In/Out	3.3 V	General-purpose digital I/O
10	GND	N/A	N/A	Ground reference
9	Data[1]	In/Out	3.3 V	General-purpose digital I/O
8	Data[0]	In/Out	3.3 V	General-purpose digital I/O
7	GND	N/A	N/A	Ground reference
6	GND	N/A	N/A	Ground reference
5	Data[9]	In/Out	3.3 V	General-purpose digital I/O
4	GND	N/A	N/A	Ground reference
3	GND	N/A	N/A	Ground reference
2	Data[8]	In/Out	3.3 V	General-purpose digital I/O
1	GND	N/A	N/A	Ground reference

Note The GPIO connector is not intended to drive large loads.

Physical Characteristics

Table 4. Dimensions and Weight

Parameter	Value
Dimensions, without connectors	17.7 cm x 11.1 cm x 1.8 cm (7.0 in. x 4.4 in. x 0.7 in.)
Dimensions, with connectors	18.8 cm x 11.1 cm x 1.8 cm (7.4 in. x 4.4 in. x 0.7 in.)
Weight	0.44 kg (0.97 lb)

Note For more information on product dimensions, visit ni.com/dimensions, search by model number, and click the appropriate link.

General Purpose I/O (GPIO)

Table 5. FPGA GPIO (through Mini HDMI Connector)

Parameter	Value
GPIOs	10
GPIO I/O voltage	+3.3 V
GPIO input VIL/VIH	0.8 V, 2.0 V
Maximum rate	50 MHz (9 ns rise/fall time, typical)
Maximum output current	250 mA VCC Out, 8 mA per GPIO output port

Timing and Reference Connectors

Table 6. Mini HDMI Sync Port – Reference Clock and PPS Outputs

Parameter	Value
Reference clock outputs	4
PPS outputs	4
Recommended accessory	NI part number 791010-01 (Mini HDMI to 8 SMAs)
Reference clock output voltage Vswing, typical	AC-coupled output ±0.325 V (0.65 V peak-peak)
Reference clock output frequencies	122.88 MHz or 125 MHz
PPS output voltage	0 V to +3.3 V

Table 7. RefClk IN SMA

Parameter	Value
Reference clock inputs	1, AC-coupled, Square Wave

Parameter	Value
Reference clock input voltage swing (with 50 Ω load)	±0.165 V to ±-0.45 V (0.33 V to 0.9 V peak-peak)
UHD driver-supported reference clock input frequencies	122.88 MHz, 125 MHz, or 10 MHz

Table 8. PPS IN SMA

Parameter	Value
PPS inputs	1, DC-coupled, Square Wave
PPS IN I/O voltage	+3.3 V (5 V tolerant)
VIL, VIH	0.8 V, 2.0 V
PPS IN timing versus rising edge of RefClk IN for deterministic PPS IN timing	• >3.5 ns setup • >2.5 ns hold

Data and System Interfaces

Table 9. Data and System Interfaces

Parameter	Value
CONSOLE JTAG	2x7 2 mm shrouded header. For use with Xilinx programming cables. Provides access to FPGA JTAG. Connector is only accessible in the USRP B310 (PCIe) and USRP B310 (OEM) variants.

Sensors

Table 10. Sensor Names and Functions

Sensor Name	Description	Return Value
ref_locked	Clock reference locked. For cases using GPS to discipline the internal clock, this sensor also checks DPLL lock.	"true" or "false"
temp_pcie_connector_edge	Temperature at the PCIe connector	°C

Sensor Name	Description	Return Value
	edge. This sensor correlates closely to the shield temperature and is included in the Enclosed Thunderbolt™ variant. Not recommended to exceed 85 °C.	
temp_fpga	Temperature of the FPGA. Not recommended to exceed 95 °C.	°C
input_voltage	Voltage at the internal Ettus USRP B310 12 V core power rail.	Volts
input_power	Power drawn from the internal Ettus USRP B310 12 V core power rail.	Watts
input_current	Current drawn from the internal Ettus USRP B310 12 V core power rail.	Amps
lmk05318_priref_valid	Detects if the input to the PRIREF of the LMK05318 is valid; input is connected to GPS Chip Timepulse.	"valid" or "invalid"
gps_pps_present	Detects if the PPS from the LMK is toggling when there is a GPS lock.	"present" or "not present"
pcie_max_speed	The maximum PCIe speed for the module.	Speed (in GT/s)
pcie_negotiated_speed	The negotiated PCIe speed for the module.	Speed (in GT/s)
pcie_max_width	The maximum PCIe link width for the module.	Link Width
pcie_negotiated_width	The negotiated PCIe link width for the module.	Link Width
gps_locked	Whether the GPS chip is locked.	"locked" or "unlocked"
gps_gpgga	The full NMEA GPGGA string.	NMEA string
gps_time	Returns the GPS epoch time.	Time (in seconds)
gps_gprmc	The full NMEA GPRMC string.	NMEA string
gps_lmk04832_lock	Returns if the LMK04832 is locked.	"locked" or "unlocked"
gps_lmk05318_dpll_freq_lock	Returns if the DPLL of the LMK05318 is frequency locked.	"locked" or "unlocked"

Sensor Name	Description	Return Value
gps_lmk05318_dpll_phase_lock	Returns if the DPLL of the LMK05318 is phase locked.	"locked" or "unlocked"
ref_stable	Clock reference has remained locked since last check.	"stable" or "lost lock"

Programmable Logic and Baseband

Table 11. Programmable Logic

FPGA model	XC7K325T-1FBG676I
FPGA speed grade	Speed Grade 1
RAM	1 GB, 800 Mbps, 32 bits wide This equates to 2.147 s of 1 channel at 125 MS/s; however, this bandwidth can be distributed across channels at supported clock rates.
Interfaces and protocols	PCIe Gen 2.0 x4

Table 12. Baseband

Supported I/Q sample rates	Default I/Q Sample Rate (Master Clock Rate) applicable for RF specifications: • 122.88 MSps Other supported rates: • 125 MSps Lower rates are supported through integer resamplers in the default UHD bitfile.
Number of available channels	2 RX, 2 TX

RF Frequency

Table 13. Frequency Characteristics

Frequency range	450 MHz to 7.125 GHz (tunable range) 350 MHz to 7.225 GHz (tunable range with band edges by way of digital offset) Digital offset automatically applied by UHD.
Frequency step	1 kHz

Table 14. Maximum Instantaneous Real-Time Bandwidth per Channel

350 MHz to 7.225 GHz	100 MHz

RF Transmitter

Notice This product is not approved or licensed for transmission over the air using a TX antenna. Operating this product with a TX antenna may violate local laws. Ensure that you comply with all local laws before operating this product with a TX antenna.

Table 15. TX Baseline Characteristics

Number of channels	2 (independent LOs shared with RX)
TX/RX switching time	1 µs, nominal
Maximum reverse power when configured to TX direction, damage level	+20 dBm, nominal

Note The Ettus USRP B310 provides two independent local oscillators (LOs). You can configure each channel (2 RX, 2 TX) to use either LO. By default, both RX channels share one LO and both TX channels share the other LO.

Table 16. TX Maximum Output Power, Typical

350 MHz to 700 MHz	≥17.6 dBm
700 MHz to 2 GHz	≥19.2 dBm
2 GHz to 4 GHz	≥14.7 dBm
4 GHz to 6 GHz	≥10.9 dBm
6 GHz to 7.15 GHz	≥8.6 dBm

Note The values listed in TX Maximum Output Power, Typical were measured at the maximum gain setting (TX Gain = 41.5 dB) using a 0 dBFS CW signal. The output power is not leveled and can be compressed.

Table 17. TX Gain Range and Step, Nominal

Analog gain range	41.5 dB
Analog gain step	0.5 dB

Table 18. TX Phase Noise

1 GHz center frequency, 1 kHz offset	−106.3 dBc/Hz
1 GHz center frequency, 10 kHz offset	−118 .6 dBc/Hz
1 GHz center frequency, 100 kHz offset	−121.1 dBc/Hz
5.8 GHz center frequency, 1 kHz offset	−91.2 dBc/Hz
5.8 GHz center frequency, 10 kHz offset	−103.7 dBc/Hz
5.8 GHz center frequency, 100 kHz offset	−105.4 dBc/Hz
7 GHz center frequency, 1 kHz offset	−89.7 dBc/Hz
7 GHz center frequency, 10 kHz offset	−101 .7 dBc/Hz
7 GHz center frequency, 100 kHz offset	− 101.5 dBc/Hz

Note The values listed in TX Phase Noise represent single-sideband phase noise, measured at TX Gain = 41.5 dB with internal reference clock.

TX Measurements

TX Error Vector Magnitude

Table 19. TX EVM Measurement Conditions

Link direction	UL
Duplex	FDD
Antenna configuration	SISO
Bandwidth	100 MHz
Subcarrier spacing	30 kHz
Modulation	256-QAM
Frequency	Tune frequency (no offset)
UHD Configured Argument TxQEC Tracking Calibration	Enabled, see *USRP B3xx Series Hardware Driver and Device Manual* for more information.

Figure 3. TX EVM Bathtub Curves, 5G NR

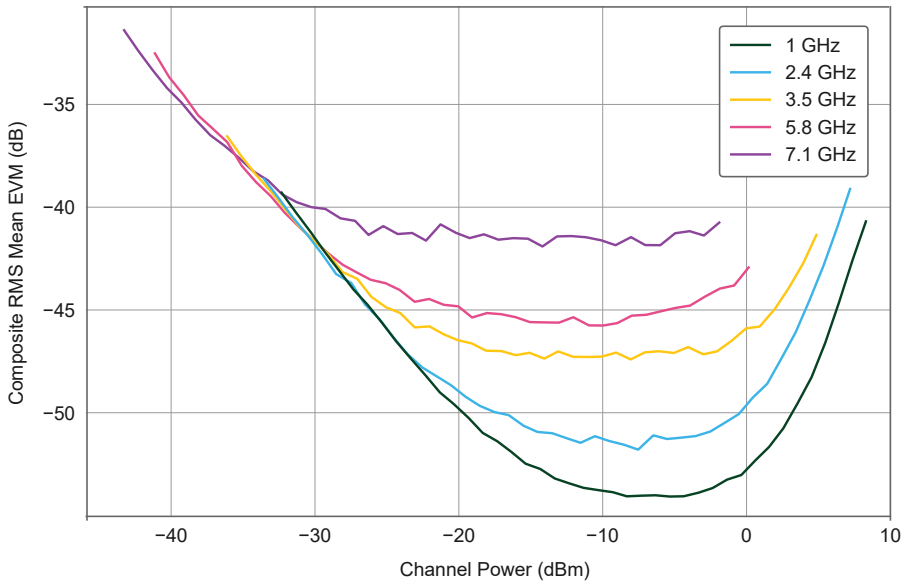
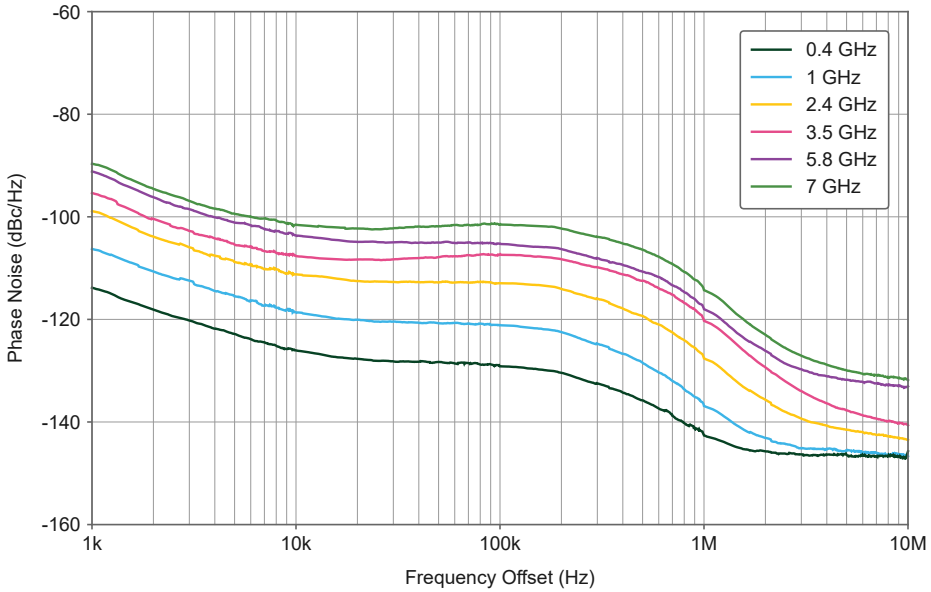


Figure 4. TX Phase Noise, Measured, MCR 122.88M



TX Output Power

Note Linear output power represents output power within the linear operating region of the transmit chain. Maximum output power can be higher and can involve gain compression and increased distortion.

Table 20. TX Output Power Measurement Conditions

Baseband level	0 dBFS
Signal type	CW
Frequency	Tune frequency

Figure 5. TX Maximum Output Power, Gain Setting Maximum

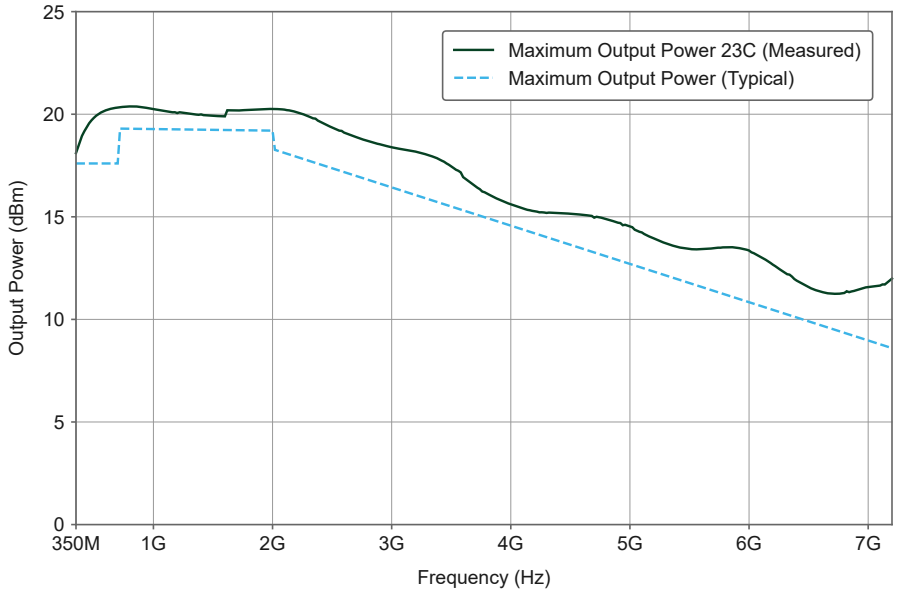
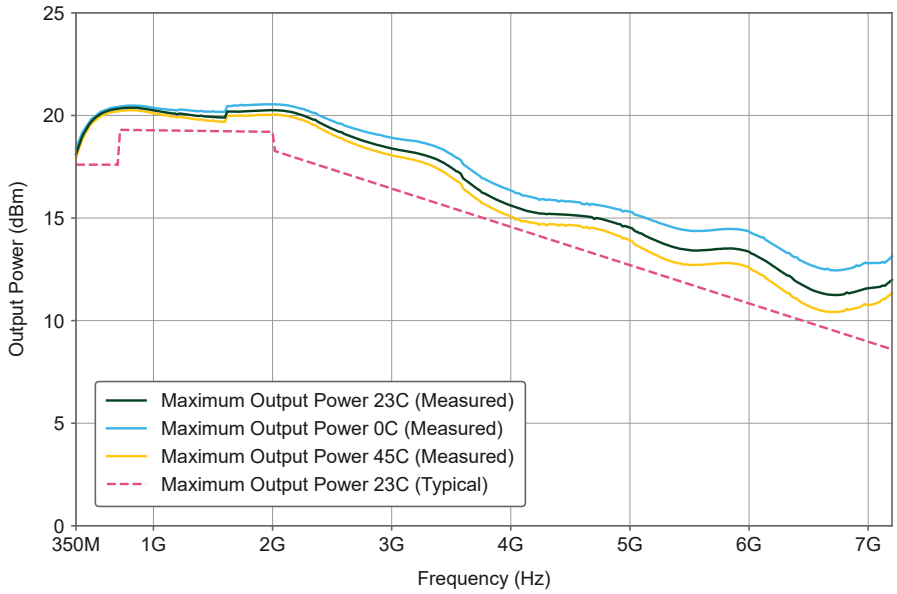


Figure 6. TX Maximum Output Power, Gain Setting Maximum, 0 °C to 50 °C



Related information:

- USRP B3xx Series Hardware Driver and Device Manual

RF Receiver

Table 21. RX Baseline Characteristics

Number of channels	2 (independent LOs shared with TX)
Maximum input power, damage level	+10 dBm, nominal

Note The Ettus USRP B310 provides two independent local oscillators (LOs). You can configure each channel (2 RX, 2 TX) to use either LO. By default, both RX channels share one LO and both TX channels share the other LO.

Notice Supplying input power in excess of the maximum input power can result in permanent device damage.

Table 22. RX Input Power to Reach 0 dBFS, at 36 dB Gain

350 MHz to 7.125 GHz	< −16 dBm

Table 23. RX Gain Range and Step, Nominal

Gain range	36 dB
Gain step	0.5 dB

Table 24. RX Noise Figure

1.0 GHz	5 dB
2.4 GHz	5.5 dB
3.5 GHz	6.3 dB
5.8 GHz	8.7 dB
7.1 GHz	10.4 dB

RX Measurements

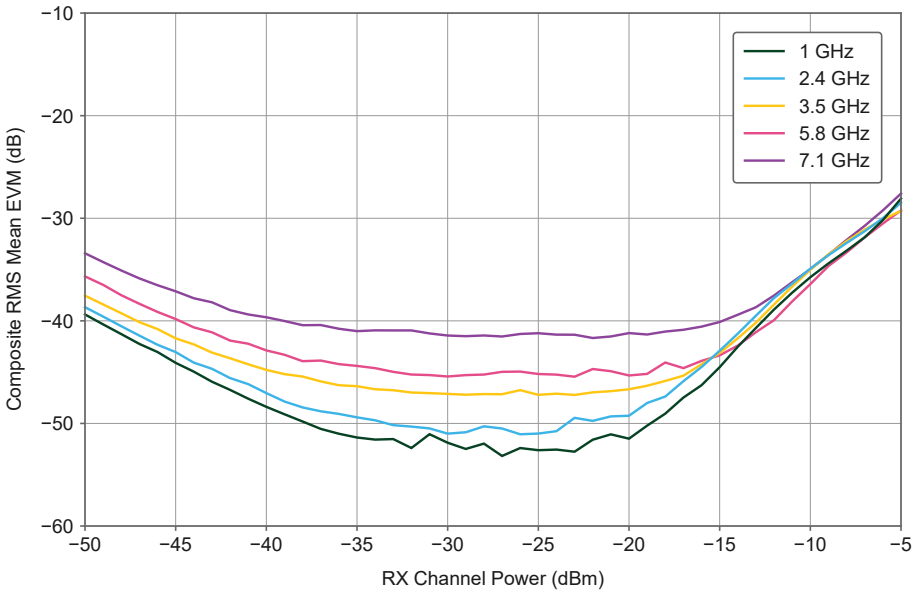
RX Error Vector Magnitude

Table 25. RX EVM Measurement Conditions

Link direction	UL
Duplex	FDD
Antenna configuration	SISO
Carrier aggregation	100 MHz
MCR	125 MHz

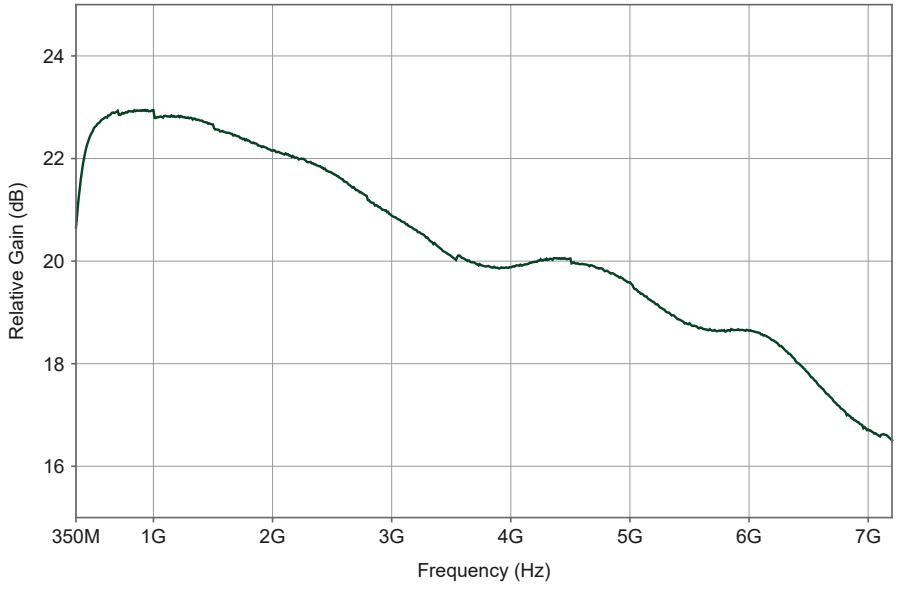
Bandwidth	30 kHz
Subcarrier spacing	256-QAM
Modulation	Tune frequency (no offset)
UHD Configured Argument RxQEC Tracking Calibration	Enabled, see *USRP B3xx Series Hardware Driver and Device Manual* for more information.

Figure 7. RX EVM Bathtub Curves, 5G NR



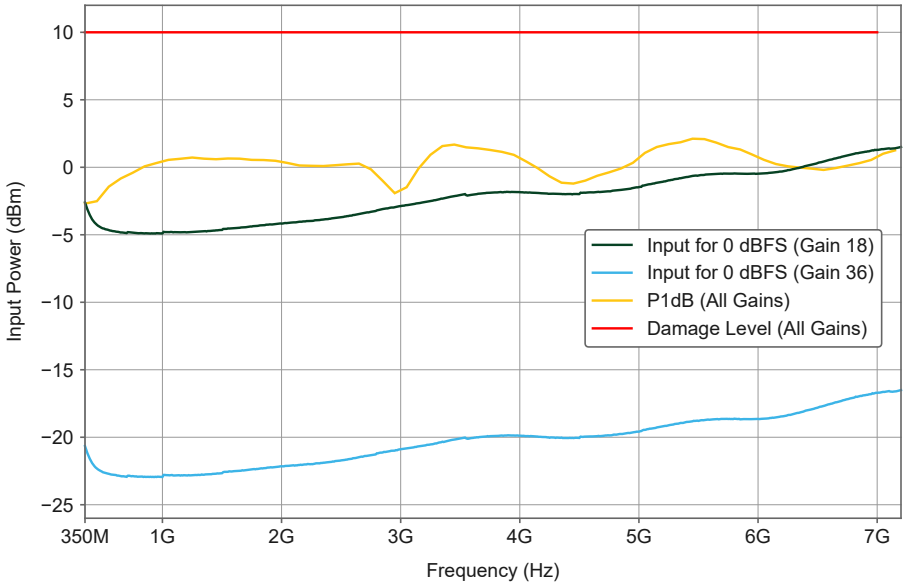
RX Input Power

Figure 8. RX Relative Gain, at 36 dB Gain



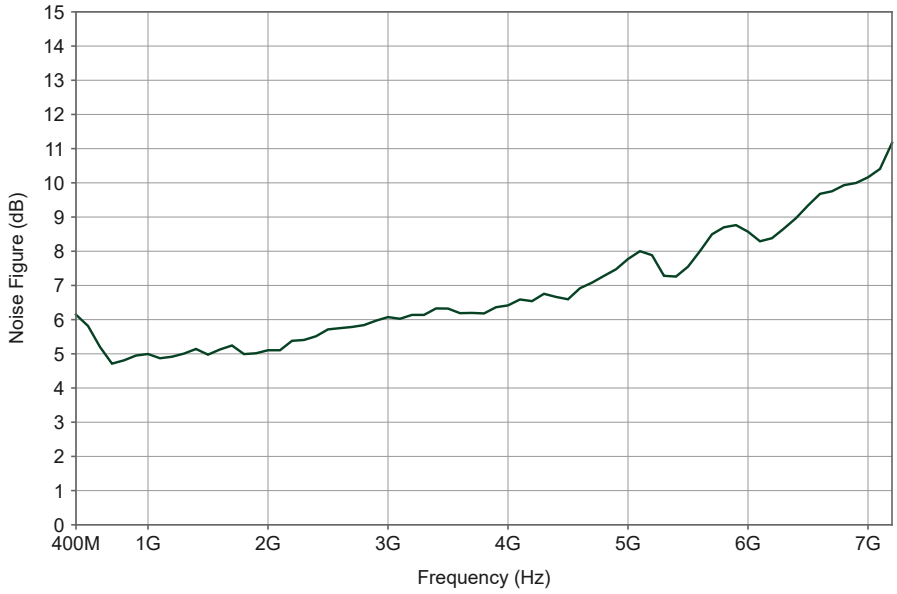
Relative gain (dB) is equal to the input power (dBm) subtracted from the measured response (dBFS).

Figure 9. RX Input Power Characterization



RX Noise Figure

Figure 10. RX Noise Figure, at 36 dB Gain



Related information:

- USRP B3xx Series Hardware Driver and Device Manual

GPS Disciplined Oscillator (GPSDO)

Table 26. Frequency Accuracy

TCXO (not locked to GPS)	2.5 ppm
TCXO (locked to GPS)	5 ppb

Table 27. Active Antenna

Type	3.0 V active antenna
Power	0.19 W
Frequency band(s)	L1C/A, E1-B/C, B1C 1.575 GHz

Power Requirements

Power Specifications

Table 28. PCIe Gen 2.0 x4 Edge Connector

Parameter	Value
Voltage rating	12 V DC @ 2.92 A
Power rating	35 W

Table 29. PCIe 2x3 Power Supply Terminal (AUX Power)

Parameter	Value
Voltage rating	12 V DC @ 2.92 A
Current/power rating	35 W



Note AUX Power is required for host devices that cannot provide at least 35 W through the PCIe Gen 2.0 x4 Edge connector.

Phase Coherency Performance



Note For phase repeatability, ensure both Numerically Controlled

Oscillators (NCOs) are not in use. Additionally, you must configure the LO frequency to a multiple SYSREF: f.LO = *N**f.SYSREF, where *N* is an integer.

For example: SYSREF = 3.84 MHz for MCR = 122.88 MHz; SYSREF = 3.90625 MHz for MCR = 125 MHz.

Definitions

- **Phase stability**—describes the short-term variation of phase and delay measured over a continuous observation window.
- **Phase repeatability**—describes the variation of phase and delay observed after configuration-changing events such as power cycles.

Table 30. Phase Coherency Performance

Configuration	Measurement	Result
Single device (sharing internal LOs)	Phase stability	<0.08° RMS
Single device (sharing internal LOs)	Phase repeatability	<0.3° RMS
Multi-device (USRP Sync Cable)	Phase stability	<1° RMS
Multi-device (USRP Sync Cable)	Phase repeatability (power cycle)	<2° RMS
Multi-device (CDA-2990)	Phase stability	<3° RMS
Multi-device (CDA-2990)	Phase repeatability (power cycle)	<10° RMS

Environmental Guidelines

Notice Failure to follow the mounting instructions in the *Ettus USRP B310 User Manual* can cause temperature derating.

Notice Use this product indoors only.

Notice Apply strain relief near the input connectors of all cables. Ensure the strain relief does not cause directional bias on the cable connectors within the input connectors.

Notice The system integrator must provide adequate cooling for the USRP B310 (OEM). Monitor the onboard **temp_fpga** sensor during operation and ensure the FPGA temperature remains below 95 °C. Additional airflow, heatsinking, or enclosure ventilation might be required depending on the application and ambient operating conditions.

Environmental Characteristics

Note In order to ensure safe operation of the USRP B310 (OEM) in end-use equipment, you must not exceed the temperature for the components in the following table. Monitor the temperature using the built-in Ettus USRP B310 FPGA temperature sensor. Do not let the temperature sensor exceed 95 °C. Refer to the *USRP Hardware Driver and Device Manual* for additional information on reading this sensor.

Notice Several factors greatly influence the USRP B310 (OEM) thermal performance. These factors include resource utilization, mounting, and adjacent power dissipation. These factors can substantially affect the achievable external ambient temperature at which the maximum local and reported temperatures are reached. NI recommends you validate your system to ensure local and reported temperatures remain within maximum allowed temperature ranges. In some applications, additional thermal design might be necessary.

Table 31. Temperature

Parameter	Value
Operating temperature[2]	-20 °C to 45 °C

2. The operating temperature is the recommended ambient temperature around the product with the PCIe variant integration (NI Part Number: 790817-01—PCIe). Higher operating temperatures might be achieved with active cooling such as fans or liquid cooling.

Parameter	Value
Storage temperature	-40 °C to 85 °C
PCIe connector edge temperature	• 85 °C maximum • PCIe connector edge temperature sensor name: "temp_pcie_connector_edge"
FPGA temperature	• 95 °C maximum • FPGA temperature sensor name: "temp_fpga"

Table 32. Humidity

Parameter	Value
Operating humidity	10% to 90% relative, non-condensing
Storage humidity	5% to 95% relative, non-condensing

Table 33. Pollution Degree

Parameter	Value
Pollution Degree	2

Table 34. Maximum Altitude

Parameter	Value
Maximum altitude	2,000 m

© 2026 National Instruments Corporation.